

1A, 50V - 1000V Glass Passivated Fast Recovery Rectifier

FEATURES

- Glass passivated chip junction
- High efficiency, Low V_F
- High current capability
- High reliability
- High surge current capability
- Low power loss
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- High frequency rectification
- Freewheeling application
- Switching mode converters and inverters in computer and telecommunication.

MECHANICAL DATA

- Case: TS-1
- Molding compound meets UL 94V-0 flammability rating
- Packing code with suffix "G" means green compound (halogen-free)
- Terminal: Pure tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Polarity: As marked
- Weight: 0.2 g (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
$I_{F(AV)}$	1	A
V_{RRM}	50 - 1000	V
I_{FSM}	30	A
T_{JMAX}	150	°C
Package	TS-1	
Configuration	Single Die	



TS-1

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)									
PARAMETER	SYMBOL	F1T1 G-K	F1T2 G-K	F1T3 G-K	F1T4 G-K	F1T5 G-K	F1T6 G-K	F1T7 G-K	UNIT
Marking code on the device		F1T1G	F1T2G	F1T3G	F1T4G	F1T5G	F1T6G	F1T7G	
Repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Reverse voltage, total rms value	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Forward current	$I_{F(AV)}$	1							A
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode	I_{FSM}	30							A
Junction temperature	T_J	- 55 to +150							°C
Storage temperature	T_{STG}	- 55 to +150							°C

CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

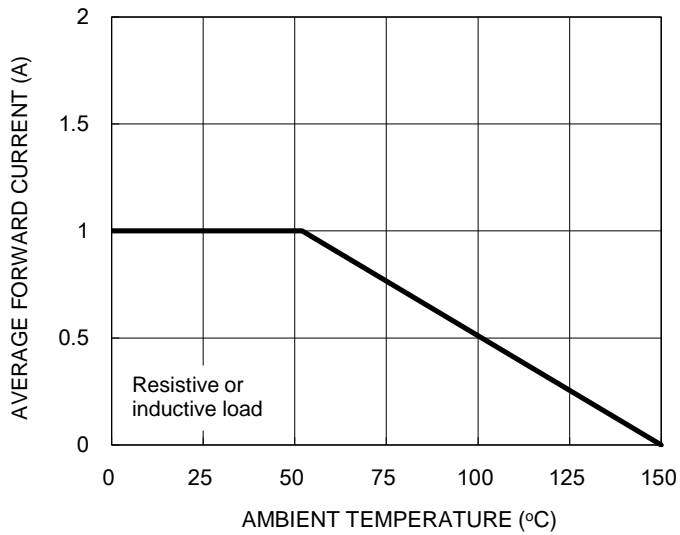


Fig.2 Typical Junction Capacitance

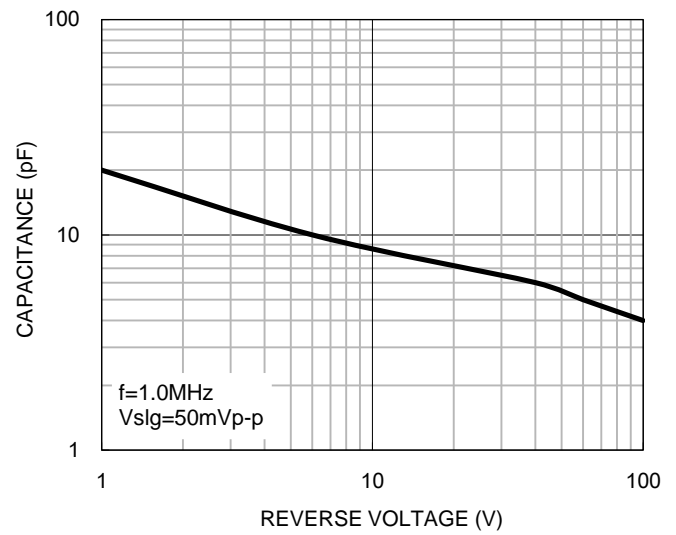


Fig.3 Typical Reverse Characteristics

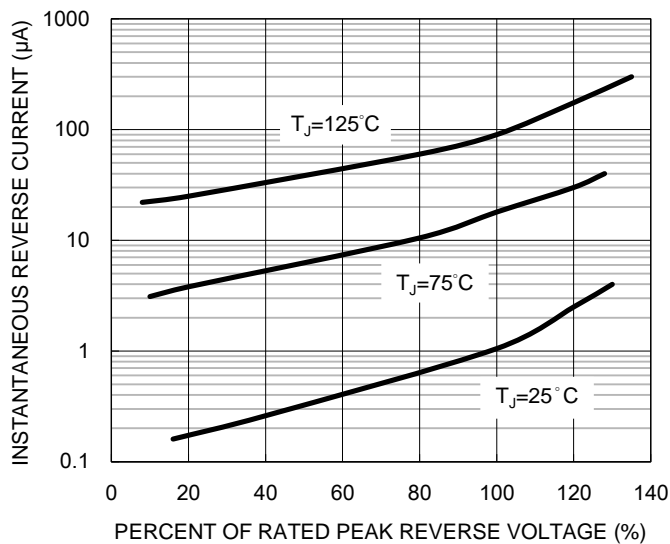
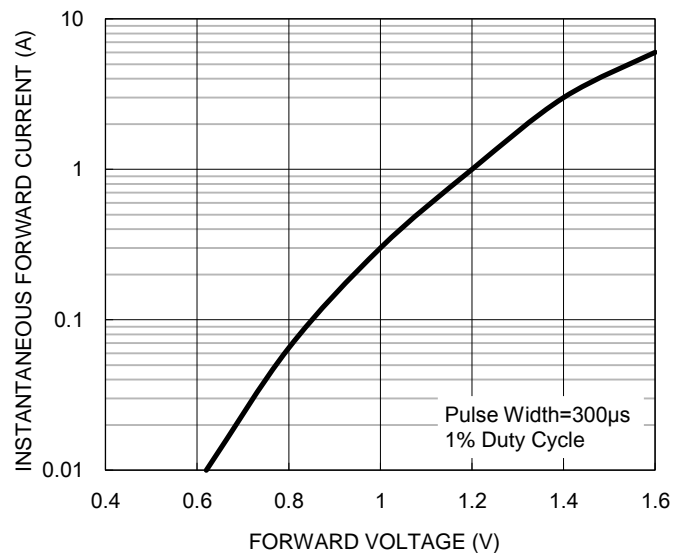


Fig.4 Typical Forward Characteristics



CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.5 Maximum Non-repetitive Forward Surge Current

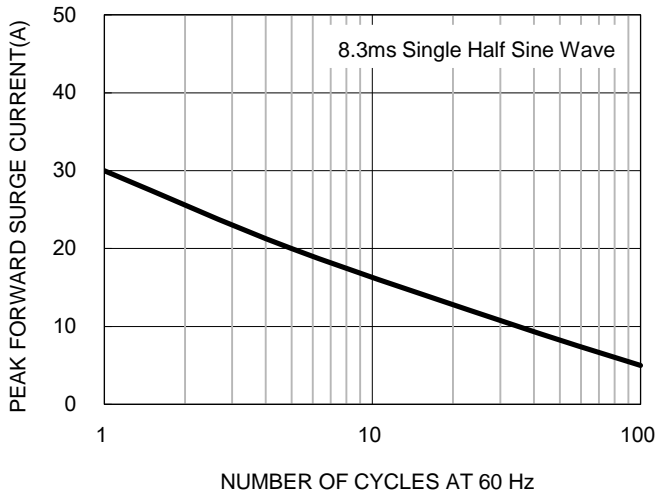
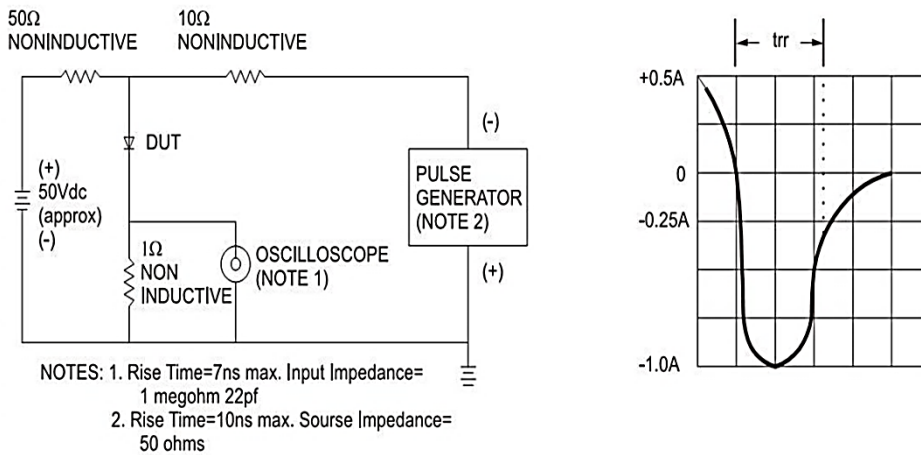
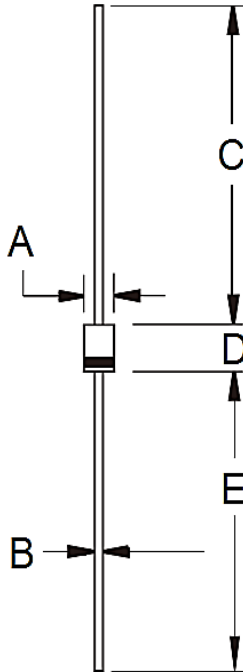


Fig.6 Reverse Recovery Time Characteristic And Test Circuit Diagram



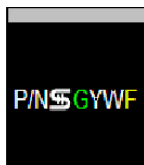
PACKAGE OUTLINE DIMENSIONS

TS-1



DIM.	Unit (mm)		Unit (inch)	
	Min	Max	Min	Max
A	2.00	2.70	0.079	0.106
B	0.53	0.64	0.021	0.025
C	25.40	-	1.000	-
D	3.00	3.30	0.118	0.130
E	25.40	-	1.000	-

MARKING DIAGRAM



- P/N = Marking Code
- G = Green Compound
- YW = Date Code
- F = Factory Code

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